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(54) **Method for bonding substrates with silicone rubber.**

(57) A method for bonding substrates with silicone rubber substantially shortens the setting time and provides good bonding of the substrates by using a silicone rubber composition comprised of a thermal-crosslinking component and moisture-crosslinking component.

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This invention relates to methods for bonding or adhering substrates using a silicone rubber composition comprised of a thermal-crosslinking component and a moisture-crosslinking component. The present invention also achieves silicone rubber bonding methods that are capable of substantially reducing the setting time and firmly bonding the substrates.

Moisture-crosslinking silicone rubber compositions crosslink at room temperature under the action of atmospheric moisture. When such compositions are crosslinked and cured while in contact with a substrate, they yield a silicone rubber that tightly bonds a variety of substrates. As a result, moisture-crosslinking silicone rubber compositions are used for adhesion applications in the very broadest range of industrial fields. For example, they are used in the construction industry for adhering window glass to aluminum frames, for adhering window glass to window glass, and for adhering tile and mortar; in the automotive industry for sealing oil pans to engine bodies, for bonding electrical circuit components on substrates, for bonding lamp bodies with lamp glass, and for bonding automotive glass to the automobile body; and in electrical/electronic sectors for adhering electronic circuit components to substrates.

Moisture-crosslinking silicone rubber compositions are exemplified by silicone rubber compositions comprised of silanol-terminated polydiorganosiloxane, curing catalyst, and organotrialkoxysilane, organotriacetoxysilane, or organotrioximosilane, and by silicone rubber compositions comprised of trialkoxysiloxy-terminated polydiorganosiloxane, curing catalyst, and organotrialkoxysilane, organotriacetoxysilane, or organotrioximosilane. Such compositions are taught in JP-A 61-247756 [247,756/1986] and JP-A 62-252456 [252,456/1987], both assigned to the same assignee as the present application.

However, crosslinking in moisture-crosslinking silicone rubber compositions develops from those regions in contact with atmospheric moisture, and as a result long periods of time are required for crosslinking in deep sections. This requirement for long setting times is a drawback associated with the use of this type of composition in continuous processes for bonding two substrates. The setting time is the time required for crosslinking to develop to such a degree that the adherends can tolerate transport and other handling for transfer to ensuing processes.

In contrast, thermal-crosslinking silicone rubber compositions are rapidly crosslinked even in deep sections by heating and are therefore used as molding materials and potting materials.

Thermal-crosslinking silicone rubber compositions are exemplified by addition reaction-crosslinking silicone rubber compositions comprised of a polydiorganosiloxane that has at least 2 alkenyl groups in each molecule, an organopolysiloxane that has at least 2 silicon-bonded hydrogen in each molecule, and a hydrosilylation catalyst. Peroxide-crosslinking silicone rubber compositions comprised of polydiorganosiloxane and organoperoxide are another example of thermal-crosslinking silicone rubber compositions.

However, these thermal-crosslinking silicone rubber compositions generally have poor adhesive properties. When this type of composition is used in continuous operations to bond two substrates, the adhesion process is complicated by the use of a preliminary primer for treatment of the substrates.

To improve the adhesive properties of thermal-crosslinking silicone rubber compositions, silicone rubber compositions comprised of a thermal-crosslinking component and a moisture-crosslinking component have been proposed in US-A 4,034,140 and US-A 4,614,760.

However, several drawbacks still occur during the continuous bonding of two substrates with silicone rubber compositions composed of a thermal-crosslinking component and a moisture-crosslinking component. Specifically, long setting times and an unsatisfactory adhesion between substrate and silicone rubber occur as in the case of conventional adhesion methods.

The inventor carried out extensive investigations in order to solve the problems described above and achieved the present invention as a result.

With regard to the adhesion or bonding of two substrates using a silicone rubber composition comprised of a thermal-crosslinking component and a moisture-crosslinking component, the present invention introduces a method for bonding substrates with silicone rubber that substantially shortens the setting time and firmly adheres the substrates to each other through the silicone rubber.

An embodiment of this invention provides a method for bonding substrates with silicone rubber comprising coating a substrate with a silicone rubber composition that comprises a thermal-crosslinking component and a moisture-crosslinking component; heating the silicone rubber composition to give a silicone gel; subsequently bringing another substrate into contact with the silicone gel; and finally forming a silicone rubber by moisture-crosslinking the silicone gel.

Another embodiment of this invention provides a method for bonding substrates with silicone rubber comprising; filling a space between two substrates with a silicone rubber composition that comprises a thermal-crosslinking component and a moisture-crosslinking component; then heating the silicone rubber composition to give a silicone gel, and finally forming a silicone rubber by moisture-crosslinking the silicone gel.

The silicone rubber composition comprised of a thermal-crosslinking component and moisture-crosslinking component of this invention has no specific restrictions with regard to execution of bonding methods. Silicone rubber compositions useful for this invention method are exemplified by the silicone rubber compositions described in US-A 4,034,140 and US-A 4,614,760.

The silicone rubber composition is also exemplified by other homogeneous blends prepared from a moisture-crosslinking silicone rubber composition plus a thermal-crosslinking silicone rubber composition. Such moisture-crosslinking silicone rubber compositions are exemplified by the combination of silanol-terminated polydiorganosiloxane, curing catalyst, and organotrialkoxysilane, organotriacetoxysilane, or organotrioximosilane; and by the combination of trialkoxysiloxy-terminated polydiorganosiloxane, curing catalyst, and organotrialkoxysilane, organotriacetoxysilane, or organotrioximosilane. The aforesaid thermal-crosslinking silicone rubber compositions are exemplified by peroxide-crosslinking silicone rubber compositions comprised of polydiorganosiloxane and organoperoxide; and by addition reaction-crosslinking silicone rubber compositions comprised of polydiorganosiloxane that has at least 2 alkenyl groups in each molecule, organopolysiloxane that has at least 2 silicon-bonded hydrogens in each molecule, and hydrosilylation catalyst. The subject silicone rubber composition may take the form of a single-package composition a two-package composition or a composition divided into an even greater number of fractions. The multipackage silicone rubber compositions are preferably mixed immediately prior to use. In addition, the silicone rubber composition under consideration may also contain inorganic filler, e.g., fumed silica, crystalline silica, calcined silica, wet-process silica, and titanium oxide; pigments such as carbon black, and iron oxide; flame retardants; and heat stabilizers.

Many varieties of substrates can be bonded with silicone rubber in accordance with the present invention. Operable substrates are inorganic substrates, such as glass, pottery, porcelain, ceramics, mortar, concrete, and slate; metal substrates, such as copper, aluminum, iron, and stainless steel; organic substrates, such as polycarbonate resin (PC resin), polyarylate resin (PAR resin), polystyrene resin, polyester resin, polybutylene resin, acrylic resin, methacrylic resin, phenolic resin, epoxy resin, polybutylene terephthalate resin (PBT resin), polyphenylene oxide resin, polyphenylene sulfide resin (PPS resin), polyamide resin, acrylonitrile/butadiene/styrene copolymer resin (ABS resin), polyimide resin, natural rubber, synthetic rubber, silicone rubber; and moldings coated with the preceding substrates, e.g., electronic components such as condensers, resistors, resin-sealed semiconductor elements. The bonding methods of the present invention are especially suitable for the bonding of heat-labile organic substrates; for example, for the bonding organic substrates such as polycarbonate resin (PC resin), acrylic resin, methacrylic resin, and polyphenylene sulfide resin (PPC resin), or moldings coated with such materials.

In the bonding method of the first embodiment, a substrate is first coated with the silicone rubber composition comprised of a thermal-crosslinking component and a moisture-crosslinking component. Many methods for applying the silicone rubber composition to the substrate can be used, and examples include extrusion from a tube or cartridge, or application from a dispenser.

The silicone rubber composition coated on the substrate is then heated to form a silicone gel. The heating temperature for silicone gel production is any temperature sufficient to yield a silicone gel from the composition. Specifically, temperatures in the range of 40°C to 200°C are preferred and temperatures in the range of 80°C to 150°C are most preferred when the composition contains alkenyl-containing organopolysiloxane, SiH-containing organopolysiloxane, and hydrosilylation catalyst. Temperatures in the range of 80°C to 250°C are preferred, and temperatures in the range of 100°C to 200°C are most preferred when the silicone rubber composition contains organoperoxide. Heating methods are exemplified by (a) holding the composition-coated substrate in a circulation oven; and (b) irradiating the composition-coated substrate with far-infrared radiation.

With regard to the silicone gel obtained by heating the silicone rubber composition in the bonding method of the first embodiment, the physical properties of this silicone gel are such that a silicone gel lacking fluidity is obtained. However, physical properties specifically preferred for this silicone gel are those having a consistency (1/4 cone) in accordance with JIS K 2220 in the range of 10 to 150 and a penetration in accordance with JIS K 2207 in the range of 10 to 600.

A second substrate is then brought into contact with the silicone gel, which results in the second substrate being held or retained on the first substrate by the silicone gel. As a consequence, the adherends become capable of withstanding transport and other handling during moisture-crosslinking of the silicone gel. Thus, shifts in the bonding position of the adherends and their delamination will be suppressed even when the silicone gel or adherends are subjected to external stresses.

Finally, the silicone gel sandwiched between the substrates is crosslinked by moisture to yield silicone rubber. The conditions for crosslinking the silicone gel are standing at room temperature in the presence of moisture without special equipment, or crosslinking of the silicone gel can be accelerated by placing it

within a device capable of maintaining elevated temperatures and high humidities.

The physical properties of the silicone rubber afforded by crosslinking of the silicone gel are such that the silicone rubber is sufficient to manifest physical properties at a level such that it can bond and hold the substrates. A specifically preferred physical property for the silicone rubber is a hardness according to JIS K 6301 in the range of 4 to 80 (spring method, type A).

In the execution of the bonding method in the second embodiment, the silicone rubber composition comprised of thermal-crosslinking component and moisture-crosslinking component is first filled into a space between two substrates. The method for filling the composition between the substrates is exemplified by extrusion from a tube or cartridge, or by application from a dispenser.

The silicone rubber composition filled between the substrates is then heated to yield a silicone gel. The heating temperature for silicone gel production is the same as described above for the first embodiment and the preferred physical properties are also the same.

The adherends are in the bonding method of the second embodiment are capable at this point of withstanding transport and other handling during moisture-crosslinking of the silicone gel. Accordingly, shifts in the bonding position of the adherends and their delamination will be suppressed even when the silicone gel or adherends are subjected to external stresses.

Finally, the silicone gel sandwiched between the substrates is crosslinked by moisture to yield silicone rubber. The conditions for crosslinking the silicone gel are the same as described for the first embodiment and the preferred physical properties are also the same.

The bonding methods in accordance with the present invention make possible a substantial shortening of the setting time and provide good bonding of the substrates with silicone rubber in the process of bonding substrates using a silicone rubber composition comprised of a thermal-crosslinking component and moisture-crosslinking component. As a result, the bonding methods in accordance with the present invention provide major improvements in productivity when used in continuous bonding processes in the electrical/electronic information-processing equipment industry, machine industry, automobile industry, rubber/plastics industry, fiber/fabric industry, and medical instrument industry.

The bonding methods of the present invention will be explained in greater detail hereinafter through working examples. The viscosities reported in the examples were measured at 25 °C. The penetration of the silicone gel, the hardness of the silicone rubber, and the adhesive properties (adhesive strength and adherence) of the silicone rubber were measured as follows.

Penetration of the silicone gel: measured in accordance with the penetration test method of JIS K 2207.

Hardness of the silicone rubber: measured by a spring-type hardness tester (type A) of JIS K 6301.

Adhesive strength of the silicone rubber: was measured against aluminum sheet by the lap shear test of JIS K 6850.

Adherence of the silicone rubber: the status of the silicone rubber was visually inspected after execution of the lap shear test of JIS K 6850 and was rated on the following scale:

- + + cohesive rupture of the silicone rubber
- + partial cohesive rupture of the silicone rubber
- x interfacial delamination

REFERENCE EXAMPLE 1

The following were added to a mixture of 50 weight parts trimethoxysiloxy-terminated polydimethylsiloxane having a viscosity of 15 Pa.s and 50 weight parts dimethylvinylsiloxy-terminated polydimethylsiloxane having a viscosity of 12 Pa.s: 10 weight parts dry-method silica (BET specific surface = 110 m²/g) whose surface had been treated with hexamethyldisilazane, 1 weight part trimethylsiloxy-terminated dimethylsiloxane-methylhydrogensiloxane copolymer (viscosity = 0.010 Pa.s, silicon-bonded hydrogen content = 0.7 weight%), sufficient isopropanolic chloroplatinic acid solution to provide 10 ppm platinum metal referred to the dimethylvinylsiloxy-terminated polydimethylsiloxane, 2 weight parts methyltrimethoxysilane, and 1 weight part tetrabutyl titanate. The resulting mixture was mixed to homogeneity while excluding moisture to obtain silicone rubber composition (I).

Silicone rubber composition (I) was held in a circulation oven at 100 °C (atmosphere = dry nitrogen) for 60 minutes to yield a silicone gel, and the penetration of this silicone gel was then measured. The hardness was also measured on the silicone rubber generated by holding this silicone gel for an additional 7 days at 20 °C/55% RH. These results are reported in Table 1.

REFERENCE EXAMPLE 2

The following were added to a mixture of 70 weight parts methyltrimethoxysiloxy-terminated polydimethylsiloxane having a viscosity of 12 Pa.s and 30 weight parts dimethylvinyl-siloxy-terminated polydimethylsiloxane having a viscosity of 12 Pa.s: 30 weight parts quartz powder, 1 weight part 2,4-dichlorobenzoyl peroxide, 2 weight parts methyltrimethoxysilane, and 0.3 weight parts diisopropoxybis(ethyl acetoacetate)-titanium. The resulting mixture was mixed, excluding moisture, to homogeneity to obtain silicone rubber composition (II).

Silicone rubber composition (II) was held in a circulation oven at 120°C (atmosphere = dry nitrogen) for 30 minutes to yield a silicone gel, and the penetration of this silicone gel was then measured. The hardness was also measured on the silicone rubber generated by holding this silicone gel for an additional 7 days at 20°C/55% RH. These results are also reported in Table 1.

REFERENCE EXAMPLE 3

The following were added to a mixture of 50 weight parts trimethylsiloxy-terminated polydimethylsiloxane having a viscosity of 12 Pa.s and 50 weight parts dimethylvinylsiloxy-terminated polydimethylsiloxane having a viscosity of 12 Pa.s, 10 weight parts dry-method silica (BET specific surface = 110 m²/g) whose surface had been treated with hexamethyldisilazane, 1 weight part trimethylsiloxy-terminated dimethylsiloxane-methylhydrogensiloxane copolymer (viscosity = 0.010 Pa.s, silicon-bonded hydrogen content = 0.7 weight%), sufficient isopropanolic chloroplatinic acid solution to provide 10 ppm platinum metal referred to the dimethylvinylsiloxy-terminated dimethylpolysiloxane, 2 weight parts methyltrimethoxysilane, and 1 weight part tetrabutyl titanate. The resulting mixture was mixed to homogeneity while excluding moisture to obtain silicone rubber composition (III).

Silicone rubber composition (III) was held in a circulation oven at 100°C (atmosphere = dry nitrogen) for 60 minutes to yield a silicone gel, and the penetration of this silicone gel was then measured. The hardness was also measured on the silicone rubber generated by holding this silicone gel for an additional 7 days at 20°C/55% RH. These results are reported in Table 1.

REFERENCE EXAMPLE 4

The following were added to a mixture of 50 weight parts trimethoxysiloxy-terminated polydimethylsiloxane having a viscosity of 15 Pa.s and 50 weight parts trimethylsiloxy-terminated polydimethylsiloxane having a viscosity of 12 Pa.s: 10 weight parts dry-method silica (BET specific surface = 110 m²/g) whose surface had been treated with hexamethyldisilazane, 1 weight part trimethylsiloxy-terminated dimethylsiloxane-methylhydrogensiloxane copolymer (viscosity = 0.010 Pa.s, silicon-bonded hydrogen content = 0.7 weight%), sufficient isopropanolic chloroplatinic acid solution to provide 10 ppm platinum metal referred to the trimethylsiloxy-terminated polydimethylsiloxane, 2 weight parts methyltrimethoxysilane, and 1 weight part tetrabutyl titanate. The resulting mixture was mixed to homogeneity while excluding moisture to obtain silicone rubber composition (IV).

Silicone rubber composition (IV) was held in a circulation oven at 100°C (atmosphere = dry nitrogen) for 60 minutes to yield a silicone gel, and the penetration of this silicone gel was then measured. The hardness was also measured on the silicone rubber generated by holding this silicone gel for an additional 7 days at 20°C/55% RH. These results are reported in Table 1.

TABLE 1

SILICONE RUBBER COMPOSITION	I	II	III	IV
Penetration after curing only by heating	50	80	45	cured only at surface
Hardness after curing by heating and moisture	20	16	1	1
Hardness after curing only by moisture	12	1	1	1

EXAMPLE 1

Silicone rubber composition (I) as prepared in Reference Example 1 was coated on an aluminum sheet. This was then held for 60 minutes in a circulation oven at 100 °C under a dry nitrogen atmosphere to form silicone gel on the aluminum sheet. Substrates as reported in Table 2 were subsequently applied to the surface of the silicone gel. In each case the substrate was bonded to the silicone gel and could not be readily delaminated from the silicone gel or knocked out of position. The substrate and aluminum sheet were bonded with silicone rubber by holding the particular assembly (substrate held on the aluminum sheet by the silicone gel) at 20 °C/55% RH for 7 days. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

COMPARISON EXAMPLE 1

Silicone rubber composition (I) as prepared in Reference Example 1 was coated on aluminum sheet, and substrates as reported in Table 2 were then respectively applied to the surface of the silicone rubber composition. The substrate and aluminum sheet were bonded with silicone rubber by holding the particular assembly (substrate held on the aluminum sheet by the silicone rubber composition) at 20 °C/55% RH for 7 days. Bonding occurred in some cases with the substrate having been knocked out of position on the aluminum sheet during transport or curing. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

EXAMPLE 2

Silicone rubber composition (I) as prepared in Reference Example 1 was filled between aluminum sheet and substrate (substrates reported in Table 2), and silicone gel was produced by holding the silicone rubber composition filled between the aluminum sheet and substrate for 60 minutes in a circulation oven at 100 °C under a dry nitrogen atmosphere. In each case the substrate was bonded to the silicone gel and could not be readily delaminated from the silicone gel or knocked out of position. The substrate and aluminum sheet were bonded by silicone rubber by holding the particular assembly (substrate held on the aluminum sheet by the silicone gel) at 20 °C/55% RH for 7 days. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

COMPARISON EXAMPLE 2

Silicone rubber composition (III) as prepared in Reference Example 3 was filled between aluminum sheet and substrate (substrates reported in Table 2), and silicone gel was produced by holding the silicone rubber composition filled between the aluminum sheet and substrate for 60 minutes in a circulation oven at 100 °C under a dry nitrogen atmosphere. In each case the substrate was bonded to the silicone gel and could not be readily delaminated from the silicone gel or knocked out of position. However, curing did not proceed any further when the particular assembly (substrate held on the aluminum sheet by the silicone gel) was held at 20 °C/55% RH for 7 days. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone gel were then respectively measured, and these results are reported in Table 2.

COMPARISON EXAMPLE 3

Silicone rubber composition (IV) as prepared in Reference Example 4 was filled between aluminum sheet and substrate (substrates reported in Table 2). Curing did not occur, however, when the silicone rubber composition filled between the aluminum sheet and substrate was held for 60 minutes in a circulation oven at 100 °C under a dry nitrogen atmosphere. The substrate and aluminum sheet were adhered by silicone rubber by holding the substrate at 20 °C/55% RH for 7 days. However, adhesion occurred in some cases with the substrate having been knocked out of position on the aluminum sheet during transport or curing. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

EXAMPLE 3

Silicone rubber composition (II) as prepared in Reference Example 2 was filled between aluminum sheet and substrate (substrates reported in Table 2), and silicone gel was produced by holding the silicone rubber composition filled between the aluminum sheet and substrate for 30 minutes in a circulation oven at 120°C under a dry nitrogen atmosphere. In each case the substrate was bonded to the silicone gel and could not be readily delaminated from the silicone gel or knocked out of position. The substrate and aluminum sheet were adhered by silicone rubber by holding the particular assembly (substrate held on the aluminum sheet by the silicone gel) at 20°C/55% RH for 7 days. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

EXAMPLE 4

Silicone rubber composition (II) as prepared in Reference Example 2 was coated on aluminum sheet. This was then held for 30 minutes in a circulation oven at 120°C under a dry nitrogen atmosphere to form silicone gel on the aluminum sheet. Substrates as reported in Table 2 were then respectively applied to the surface of the silicone gel. In each case the substrate was bonded to the silicone gel and could not be readily delaminated from the silicone gel or knocked out of position. The substrate and aluminum sheet were adhered by silicone rubber by holding the particular assembly (substrate held on the aluminum sheet by the silicone gel) at 20°C/55% RH for 7 days. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

COMPARISON EXAMPLE 4

Silicone rubber composition (II) as prepared in Reference Example 2 was filled between aluminum sheet and substrate (substrates reported in Table 2). The aluminum sheet and substrate were adhered by silicone rubber by holding the silicone rubber composition filled between the aluminum sheet and substrate for 7 days at 20°C/55% RH. Adhesion occurred in some cases with the substrate having been knocked out of position on the aluminum sheet during transport or curing. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

COMPARISON EXAMPLE 5

Specimens prepared as in Comparison Example 4 (assembly of aluminum sheet and substrate adhered by silicone rubber) were additionally held for 30 minutes in a circulation oven at 120°C. The adhesive strength and adherence between the aluminum sheet and substrate due to the silicone rubber were then respectively measured, and these results are reported in Table 2.

TABLE 2

	Example 1	Invention Example 2	Examples Example 3	Example 4
Adhesive strength (kgf/cm ²)	10	11	9	8
Adherence:				
Substrate:				
Aluminum sheet	+	+	+	+
Stainless steel sheet	+	+	+	+
Glass sheet	+	+	+	+
PC resin sheet*	+	+	+	+
PPS resin sheet*	+	+	+	+

TABLE 2 (continued from above)

	Comp. Ex. 1	Comp. Ex. 2	Comparison Comp. Ex. 3	Examples Comp. Ex. 4	Comp. Ex. 5
Adhesive strength (kgf/cm)	5	4	3	5	7
Adherence:					
Substrate:					
Aluminum sheet	+	x	+	+	+
Stainless steel sheet	x	x	x	x	x
Glass sheet	+	x	+	+	+
PC resin sheet*	x	x	x	x	x
PPS resin sheet*	x	x	x	x	x

* PC resin sheet = sheet of polycarbonate resin
 PPS resin sheet = sheet of polyphenylene sulfide resin

The bonding methods of the present invention are characterized by their ability to substantially shorten the setting time and provide good bonding of the substrates with silicone rubber in the process of bonding substrates using a silicone rubber composition comprised of a thermal-crosslinking component and moisture-crosslinking component.

Claims

1. A method for bonding substrates with silicone rubber comprising coating a substrate with a silicone rubber composition comprising a thermal-crosslinking component and a moisture-crosslinking component, then heating the silicone rubber composition to give a silicone gel, then subsequently bringing another substrate into contact with the silicone gel, and finally forming a silicone rubber by moisture-crosslinking the silicone gel.
2. A method for bonding substrates with silicone rubber comprising filling a space between two substrates with a silicone rubber composition that comprises a thermal-crosslinking component and a moisture-crosslinking component, then heating the silicone rubber composition to give a silicone gel, and finally forming a silicone rubber by moisture-crosslinking the silicone gel.



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EUROPEAN SEARCH REPORT

Application Number
EP 94 10 7650

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.CLS)
A	EP-A-0 455 361 (DOW CORNING) ---		C09J5/06 C09J5/00 C09J183/04
A	EP-A-0 012 825 (TH. GOLDSCHMIDT) -----		
			TECHNICAL FIELDS SEARCHED (Int.CLS)
			C09J
The present search report has been drawn up for all claims			
Place of search THE HAGUE		Date of completion of the search 9 September 1994	Examiner Leroy, A
CATEGORY OF CITED DOCUMENTS			
X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document		T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons ----- & : member of the same patent family, corresponding document	

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